

United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

| APPLICATION NO. | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. |
|--|---------------|----------------------|-------------------------|------------------|
| 10/797,923 | 03/10/2004 | Shoichi Furuhata | FUJI:300 | 3352 |
| 37013 75 | 90 04/21/2005 | EXAMINER | | |
| ROSSI & ASSOCIATES | | | DICKEY, THOMAS L | |
| P.O. BOX 826 ASHBURN, VA 20146-0826 | | | ART UNIT | PAPER NUMBER |
| | | | 2826 | |
| | | | DATE MAILED: 04/21/2005 | |

Please find below and/or attached an Office communication concerning this application or proceeding.

Application/Control Number: 10/797,923

Page 2

Art Unit: 2826

DETAILED ACTION

Election/Restriction

1. Applicant's election of Group II, claims 1-9 in the Paper filed 03/31/2005 is acknowledged. Because applicant did not distinctly and specifically point out the supposed errors in the restriction requirement, the election has been treated as an election without traverse (MPEP § 818.03(a)).

Oath/Declaration

2. The oath/declaration filed on 03/10/2004 is acceptable.

Drawings

3. The formal drawings filed on 03/10/2004 are acceptable.

Priority

4. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

Application/Control Number: 10/797,923 Page 3

Art Unit: 2826

Information Disclosure Statement

5. The Information Disclosure Statement filed on 03/10/2004 has been considered.

Claim Rejections - 35 USC § 102

6. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless --

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-5,7, and 8 are rejected under 35 U.S.C. 102(b) as being anticipated by BOSSELAAR ET AL. (4,148,053).

With regard to claims 1-3, Bosselaar et al. discloses a semiconductor wafer comprising a first conduction type low concentration impurity layer 1 formed beneath a principal face of a wafer to a predetermined depth; a first conduction type high concentration impurity layer 2 having an impurity concentration (note column 4 lines 19-20) of 5X1019/cc (and thus, inherently, resistance value not higher than 0.05 Ω•cm, note figure 6 of Kroger 4;544,937) underlying said low concentration impurity layer 1; and a first conduction type high concentration impurity diffusion region 6 having a lattice-shaped pattern (Note figure 2 of

Art Unit: 2826

Rowe 4,040,878, which is incorporated by reference into Bosselaar et al. at column 4 line 60), formed along at least a portion of the dicing lines A-A that delimit a plurality of chips (again, the plurality of chips is seen most clearly in figure 2 of Rowe 4,040,878, which is incorporated by reference into Bosselaar et al.) on said wafer, said diffusion region 6 extending from the principal face of the wafer to said high concentration impurity layer 2, wherein said diffusion region 6 has a width larger than that of the cutting allowance for the dicing along the dicing lines A-A. Note figures 4-6, column 4 lines 19, 20, and 49-64, column 5 lines 56-60, and column 6 lines 35-39 of Bosselaar et al.

With regard to claims 4, 5, 7, and 8, Bosselaar et al. discloses a semiconductor wafer comprising a first conduction type low concentration impurity layer 1; a first conduction type high concentration impurity layer 2 having an impurity concentration (note column 4 lines 19-20) of 5X1019/cc (and thus, inherently, resistance value not higher than 0.05 Ω•cm, note figure 6 of Kroger 4,544,937) underlying said low concentration impurity layer 1; and a first conduction type high concentration impurity diffusion region 6 that extends from the upper surface of said low concentration impurity layer 1 to said high concentration impurity layer 2, said diffusion region 6 being positioned at the outer edge of an element region 3 having a semiconductor element 4 formed therein; wherein said diffusion region 6 comprises a

Page 5

Art Unit: 2826

portion or the entirety of dicing regions A-A on a wafer containing said device, wherein said high concentration impurity diffusion region 6 electrically connects said high concentration impurity layer 2 with at least one electrode 35 positioned above said low concentration impurity layer 1, by being electrically connected with at least one electrode 35 formed on the upper surface of said low concentration impurity layer 1. Note figures 4-6, column 4 lines 19, 20, and 49-64, column 5 lines 56-60, and column 6 lines 35-39 of Bosselaar et al.

Allowable Subject Matter

7. Claims 6 and 9 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Conclusion

8. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thomas L Dickey whose telephone number is 571-272-1913. The examiner can normally be reached on Monday-Thursday 8-6.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan J Flynn can be reached on 571-272-1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Application/Control Number: 10/797,923 Page 6

Art Unit: 2826

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Thomas L. Dickey Patent Examiner Art Unit 2826 04/05

Chol-Ding